

Excilibur™ LOW-NOISE HIGH-SPEED PRECISION OPERATIONAL AMPLIFIERS

Check for Samples: [TLE2141-Q1](#)

FEATURES

- **Qualified for Automotive Applications**
- **Low Noise**
 - 10 Hz ... 15 nV/√Hz
 - 1 kHz ... 10.5 nV/√Hz
- **10000-pF Load Capability**
- **20-mA Min Short-Circuit Output Current**
- **27-V/μs Slew Rate (Min)**
- **High Gain-Bandwidth Product ... 5.9 MHz**
- **Low V_{IO} ... 500 μV (Max) at 25°C**
- **Single or Split Supply ... 4 V to 44 V**
- **Fast Settling Time**
 - 340 ns to 0.1%
 - 400 ns to 0.01%
- **Saturation Recovery ... 150 ns**
- **Large Output Swing ... $V_{CC-} + 0.1\text{ V}$ to $V_{CC+} - 1\text{ V}$**

DESCRIPTION

The TLE2141-Q1 device is a high-performance, internally compensated operational amplifier built using the Texas Instruments complementary bipolar Excilibur™ process. It is a pin-compatible upgrade to standard industry products.

The design incorporates an input stage that simultaneously achieves low audio-band noise of 10.5 nV/√Hz with a 10-Hz 1/f corner and symmetrical 40-V/μs slew rate typically with loads up to 800 pF. The resulting low distortion and high power bandwidth are important in high-fidelity audio applications. A fast settling time of 340 ns to 0.1% of a 10-V step with a 2-kΩ/100-pF load is useful in fast actuator/positioning drivers. Under similar test conditions, settling time to 0.01% is 400 ns.

The device is stable with capacitive loads up to 10 nF, although the 6-MHz bandwidth decreases to 1.8 MHz at this high loading level. As such, the TLE2141-Q1 is useful for low-droop sample-and-holds and direct buffering of long cables, including 4-mA to 20-mA current loops.

The special design also exhibits an improved insensitivity to inherent integrated circuit component mismatches as is evidenced by a 500-μV maximum offset voltage and 1.7-μV/°C typical drift. Minimum common-mode rejection ratio and supply-voltage rejection ratio are 85 dB and 90 dB, respectively.

Device performance is relatively independent of supply voltage over the ±2-V to ±22-V range. Inputs can operate between $V_{CC-} - 0.3\text{ V}$ to $V_{CC+} - 1.8\text{ V}$ without inducing phase reversal, although excessive input current may flow out of each input exceeding the lower common-mode input range. The all-npn output stage provides a nearly rail-to-rail output swing of $V_{CC-} - 0.1\text{ V}$ to $V_{CC+} - 1\text{ V}$ under light current-loading conditions. The device can sustain shorts to either supply since output current is internally limited, but care must be taken to ensure that maximum package power dissipation is not exceeded.

The TLE2141-Q1 device can also be used as a comparator. Differential inputs of $V_{CC\pm}$ can be maintained without damage to the device. Open-loop propagation delay with TTL supply levels is typically 200 ns. This gives a good indication as to output stage saturation recovery when the device is driven beyond the limits of recommended output swing.

The TLE2141-Q1 device is available in industry-standard 8-pin package. The device is characterized for operation from –40°C to 125°C.

ORDERING INFORMATION⁽¹⁾

T_A	PACKAGE		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 125°C	SOIC – D (8 pin)	Reel of 2500	TLE2141QDRQ1	2141Q

(1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at [www.ti.com](#).

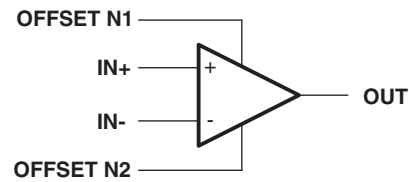
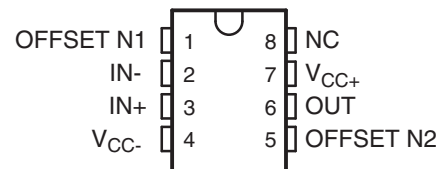


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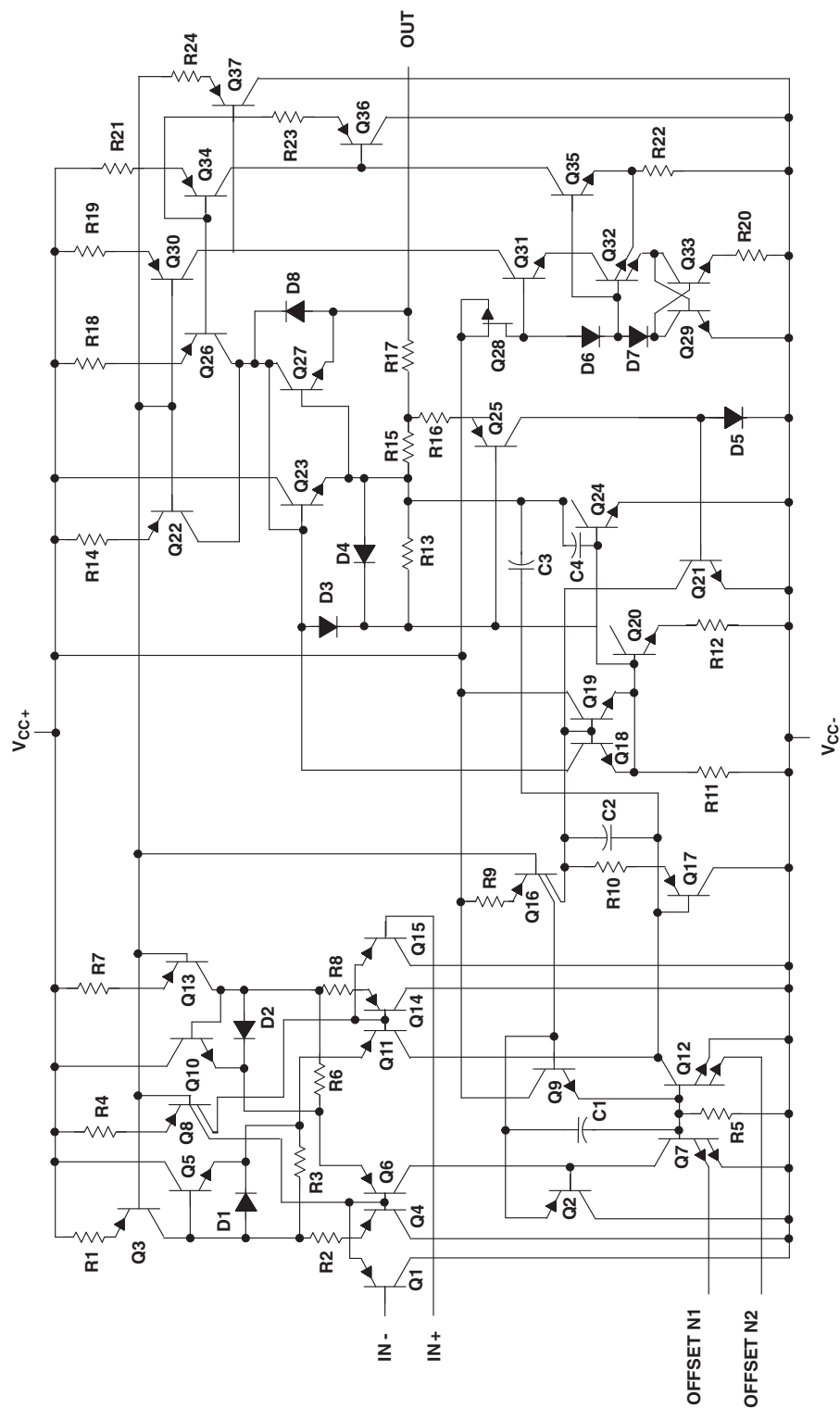
PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of the Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

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SYMBOL**D PACKAGE
(TOP VIEW)**

NC – No internal connection

Figure 1. EQUIVALENT SCHEMATIC



DEVICE COMPONENT COUNT

COMPONENT	TLE2141-Q1
Transistors	46
Resistors	24
Diodes	8
Capacitors	4
Epi-FET	1

ABSOLUTE MAXIMUM RATINGS⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

		VALUE	UNIT
V_{CC+}	Supply voltage ⁽²⁾	22	V
V_{CC-}	Supply voltage	-22	V
V_{ID}	Differential input voltage ⁽³⁾	± 44	V
V_I	Input voltage range (any input)	V_{CC+} to $(V_{CC-} - 0.3)$	V
I_I	Input current (each input)	± 1	mA
I_O	Output current	± 80	mA
	Total current into V_{CC+}	80	mA
	Total current out of V_{CC-}	80	mA
	Duration of short-circuit current at (or below) 25°C ⁽⁴⁾	Unlimited	
θ_{JA}	Package thermal impedance ⁽⁵⁾ ⁽⁶⁾	D package (8 pin)	°C/W
T_A	Operating free-air temperature range	-40 to 125	°C
T_{stg}	Storage temperature range	-65 to 150	°C
	Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260	°C

- (1) Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) All voltage values, except differential voltages, are with respect to the midpoint between V_{CC+} and V_{CC-} .
- (3) Differential voltages are at $IN+$ with respect to $IN-$. Excessive current flows, if input, are brought below $V_{CC-} - 0.3$ V.
- (4) The output may be shorted to either supply. Temperature and/or supply voltages must be limited to ensure that the maximum dissipation rating is not exceeded.
- (5) Maximum power dissipation is a function of $T_J(\text{max})$, θ_{JA} , and T_A . The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(\text{max}) - T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can affect reliability.
- (6) The package thermal impedance is calculated in accordance with JESD 51-7.

RECOMMENDED OPERATING CONDITIONS

			MIN	MAX	UNIT
V _{CC±}	Supply voltage		±2	±22	V
V _{IC}	Common-mode input voltage	V _{CC} = 5 V	0	2.7	V
		V _{CC±} = ±15 V	−15	12.7	
T _A	Operating free-air temperature		−40	125	°C

ELECTRICAL CHARACTERISTICS

 $V_{CC} = 5\text{ V}$, at specified free-air temperature (unless otherwise noted)

PARAMETER	TEST CONDITIONS	T_A ⁽¹⁾	MIN	TYP	MAX	UNIT
V_{IO} Input offset voltage	$V_O = 2.5\text{ V}$, $R_S = 50\ \Omega$, $V_{IC} = 2.5\text{ V}$	25°C		225	1400	μV
		Full range			2100	
α_{VIO} Temperature coefficient of input offset voltage	$V_O = 2.5\text{ V}$, $R_S = 50\ \Omega$, $V_{IC} = 2.5\text{ V}$	Full range		1.7		$\mu\text{V}/^\circ\text{C}$
I_{IO} Input offset current	$V_O = 2.5\text{ V}$, $R_S = 50\ \Omega$, $V_{IC} = 2.5\text{ V}$	25°C		8	100	nA
		Full range			250	
I_{IB} Input bias current	$V_O = 2.5\text{ V}$, $R_S = 50\ \Omega$, $V_{IC} = 2.5\text{ V}$	25°C		–0.8	–2	μA
		Full range			–2.3	
V_{ICR} Common-mode input voltage range	$R_S = 50\ \Omega$	25°C	0 to 3	–0.3 to 3.2		V
		Full range	0 to 2.7	–0.3 to 2.9		
V_{OH} High-level output voltage	$I_{OH} = -150\ \mu\text{A}$ $I_{OH} = -1.5\text{ mA}$ $I_{OH} = -15\text{ mA}$	25°C	3.9	4.1		V
			3.8	4		
			3.2	3.7		
	$I_{OH} = -100\ \mu\text{A}$ $I_{OH} = -1\text{ mA}$ $I_{OH} = -10\text{ mA}$	Full range	3.75			
			3.65			
			3.25			
V_{OL} Low-level output voltage	$I_{OL} = 150\ \mu\text{A}$ $I_{OL} = 1.5\text{ mA}$ $I_{OL} = 15\text{ mA}$	25°C		75	125	mV
				150	225	
				1.2	1.4	V
	$I_{OL} = 100\ \mu\text{A}$ $I_{OL} = 1\text{ mA}$ $I_{OL} = 10\text{ mA}$	Full range		200		mV
				250		
				1.25		V
A_{VD} Large-signal differential voltage amplification	$V_{IC} = \pm 2.5\text{ V}$, $R_L = 2\text{ k}\Omega$, $V_O = 1\text{ V to } 1.5\text{ V}$	25°C	50	220		V/mV
		Full range	5			
r_i Input resistance		25°C		70		M Ω
c_i Input capacitance		25°C		2.5		pF
z_o Open-loop output impedance	$f = 1\text{ MHz}$	25°C		30		Ω
CMRR Common-mode rejection ratio	$V_{IC} = V_{ICR}(\text{min})$, $R_S = 50\ \Omega$	25°C	85	118		dB
		Full range	80			
k_{SVR} Supply-voltage rejection ratio ($\Delta V_{CC\pm}/\Delta V_{IO}$)	$V_{CC\pm} = \pm 2.5\text{ V to } \pm 15\text{ V}$, $R_S = 50\ \Omega$	25°C	90	106		dB
		Full range	85			
I_{CC} Supply current	$V_O = 2.5\text{ V}$, No load, $V_{IC} = 2.5\text{ V}$	25°C		3.4	4.4	mA
		Full range			4.6	

(1) Full range is –40°C to 125°C.

OPERATING CHARACTERISTICS

$V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$ (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
SR+	Positive slew rate	$A_{VD} = -1$, $R_L = 2\text{ k}\Omega^{(1)}$, $C_L = 500\text{ pF}$		45		V/ μs
SR–	Negative slew rate	$A_{VD} = -1$, $R_L = 2\text{ k}\Omega^{(1)}$, $C_L = 500\text{ pF}$		42		V/ μs
t_s	Settling time	$A_{VD} = -1$, 2.5-V step	To 0.1%	0.16		μs
			To 0.01%	0.22		
V_n	Equivalent input noise voltage	$R_S = 20\ \Omega$	$f = 10\text{ Hz}$	15		$\text{nV}/\sqrt{\text{Hz}}$
			$f = 1\text{ kHz}$	10.5		
$V_{n(PP)}$	Peak-to-peak equivalent input noise voltage	$f = 0.1\text{ Hz to }1\text{ Hz}$		0.48		μV
		$f = 0.1\text{ Hz to }10\text{ Hz}$		0.51		
I_n	Equivalent input noise current	$f = 10\text{ Hz}$		1.92		$\text{pA}/\sqrt{\text{Hz}}$
		$f = 1\text{ kHz}$		0.5		
THD+N	Total harmonic distortion plus noise	$V_O = 1\text{ V to }3\text{ V}$, $R_L = 2\text{ k}\Omega^{(1)}$, $A_{VD} = 2$, $f = 10\text{ kHz}$		0.0052		%
B_1	Unity-gain bandwidth	$R_L = 2\text{ k}\Omega^{(1)}$, $C_L = 100\text{ pF}^{(1)}$		5.9		MHz
	Gain-bandwidth product	$R_L = 2\text{ k}\Omega^{(1)}$, $C_L = 100\text{ pF}^{(1)}$, $f = 100\text{ kHz}$		5.8		MHz
BOM	Maximum output-swing bandwidth	$V_{O(PP)} = 2\text{ V}$, $R_L = 2\text{ k}\Omega^{(1)}$, $A_{VD} = 1$		660		kHz
Φ_m	Phase margin at unity gain	$R_L = 2\text{ k}\Omega^{(1)}$, $C_L = 100\text{ pF}^{(1)}$		57		°

(1) R_L and C_L terminated to 2.5 V.

ELECTRICAL CHARACTERISTICS

 $V_{CC} = \pm 15\text{ V}$, at specified free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS	T_A ⁽¹⁾	MIN	TYP	MAX	UNIT
V_{IO}	Input offset voltage	$V_{IC} = 0$, $R_S = 50\ \Omega$	25°C		200	900	μV
			Full range			1700	
α_{VIO}	Temperature coefficient of input offset voltage	$V_{IC} = 0$, $R_S = 50\ \Omega$	Full range		1.7		$\mu\text{V}/^\circ\text{C}$
I_{IO}	Input offset current	$V_{IC} = 0$, $R_S = 50\ \Omega$	25°C		7	100	nA
			Full range			250	
I_{IB}	Input bias current	$V_{IC} = 0$, $R_S = 50\ \Omega$	25°C		–0.7	–1.5	μA
			Full range			–1.8	
V_{ICR}	Common-mode input voltage range	$R_S = 50\ \Omega$	25°C	–15 to 13	–15.3 to 13.2		V
			Full range	–15 to 12.7	–15.3 to 12.9		
V_{OM+}	Maximum positive peak output voltage swing	$I_O = -150\ \mu\text{A}$	25°C	13.8	14.1		V
		$I_O = -1.5\ \text{mA}$		13.7	14		
		$I_O = -15\ \text{mA}$		13.1	13.7		
		$I_O = -100\ \mu\text{A}$	Full range	13.7			
		$I_O = -1\ \text{mA}$		13.6			
		$I_O = -10\ \text{mA}$		13.1			
V_{OM-}	Maximum negative peak output voltage swing	$I_O = 150\ \mu\text{A}$	25°C	–14.7	–14.9		V
		$I_O = 1.5\ \text{mA}$		–14.5	–14.8		
		$I_O = 15\ \text{mA}$		–13.4	–13.8		
		$I_O = 100\ \mu\text{A}$	Full range	–14.6			
		$I_O = 1\ \text{mA}$		–14.5			
		$I_O = 10\ \text{mA}$		–13.4			
A_{VD}	Large-signal differential voltage amplification	$V_O = \pm 10\ \text{V}$, $R_L = 2\ \text{k}\Omega$	25°C	100	450		V/mV
			Full range	20			
r_i	Input resistance		25°C		65		M Ω
c_i	Input capacitance		25°C		2.5		pF
z_o	Open-loop output impedance	$f = 1\ \text{MHz}$	25°C		30		Ω
CMRR	Common-mode rejection ratio	$V_{IC} = V_{ICR}(\text{min})$, $R_S = 50\ \Omega$	25°C	85	108		dB
			Full range	80			
k_{SVR}	Supply-voltage rejection ratio ($\Delta V_{CC\pm}/\Delta V_{IO}$)	$V_{CC\pm} = \pm 2.5\ \text{V}$ to $\pm 15\ \text{V}$, $R_S = 50\ \Omega$	25°C	90	106		dB
			Full range	85			
I_{OS}	Short-circuit output current	$V_O = 0$	25°C	–25	–50		mA
				20	31		
I_{CC}	Supply current	$V_O = 0$, No load, $V_{IC} = 2.5\ \text{V}$	25°C		3.5	4.5	mA
			Full range			4.7	

(1) Full range is –40°C to 125°C.

OPERATING CHARACTERISTICS

$V_{CC} = \pm 15\text{ V}$, $T_A = 25^\circ\text{C}$ (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
SR+	Positive slew rate	$A_{VD} = -1$, $R_L = 2\text{ k}\Omega$, $C_L = 100\text{ pF}$	27	45		V/ μs
SR–	Negative slew rate	$A_{VD} = -1$, $R_L = 2\text{ k}\Omega$, $C_L = 100\text{ pF}$	27	42		V/ μs
t_s	Settling time	$A_{VD} = -1$, 10-V step	To 0.1%	0.34		μs
			To 0.01%	0.4		
V_n	Equivalent input noise voltage	$R_S = 20\text{ }\Omega$	$f = 10\text{ Hz}$	15		$\text{nV}/\sqrt{\text{Hz}}$
			$f = 1\text{ kHz}$	10.5		
$V_{n(PP)}$	Peak-to-peak equivalent input noise voltage	$f = 0.1\text{ Hz to }1\text{ Hz}$		0.48		μV
		$f = 0.1\text{ Hz to }10\text{ Hz}$		0.51		
I_n	Equivalent input noise current	$f = 10\text{ Hz}$		1.89		$\text{pA}/\sqrt{\text{Hz}}$
		$f = 1\text{ kHz}$		0.47		
THD+N	Total harmonic distortion plus noise	$V_{O(PP)} = 20\text{ V}$, $R_L = 2\text{ k}\Omega$, $A_{VD} = 10$, $f = 10\text{ kHz}$		0.01		%
B_1	Unity-gain bandwidth	$R_L = 2\text{ k}\Omega$, $C_L = 100\text{ pF}$		6		MHz
	Gain-bandwidth product	$R_L = 2\text{ k}\Omega$, $C_L = 100\text{ pF}$, $f = 100\text{ kHz}$		5.9		MHz
BOM	Maximum output-swing bandwidth	$V_{O(PP)} = 20\text{ V}$, $A_{VD} = 1$, $R_L = 2\text{ k}\Omega$, $C_L = 100\text{ pF}$		668		kHz
ϕ_m	Phase margin at unity gain	$R_L = 2\text{ k}\Omega$, $C_L = 100\text{ pF}$		58		°

TYPICAL CHARACTERISTICS

Table 1. Table of Graphs

V_{IO}	Input offset voltage	Distribution	Figure 2
I_{IO}	Input offset current	vs Free-air temperature	Figure 3
I_{IB}	Input bias current	vs Common-mode input voltage	Figure 4
		vs Free-air temperature	Figure 5
V_{OM+}	Maximum positive peak output voltage	vs Supply voltage	Figure 6
		vs Free-air temperature	Figure 7
		vs Output current	Figure 8
		vs Settling time	Figure 10
V_{OM-}	Maximum negative peak output voltage	vs Supply voltage	Figure 6
		vs Free-air temperature	Figure 7
		vs Output current	Figure 9
		vs Settling time	Figure 10
$V_{O(PP)}$	Maximum peak-to-peak output voltage	vs Frequency	Figure 11
V_{OH}	High-level output voltage	vs Output current	Figure 12
V_{OL}	Low-level output voltage	vs Output current	Figure 13
	Phase shift	vs Frequency	Figure 14
A_{VD}	Large-signal differential voltage amplification	vs Frequency	Figure 14
		vs Free-air temperature	Figure 15
z_o	Closed-loop output impedance	vs Frequency	Figure 16
I_{OS}	Short-circuit output current	vs Free-air temperature	Figure 17
CMRR	Common-mode rejection ratio	vs Frequency	Figure 18
		vs Free-air temperature	Figure 19
k_{SVR}	Supply-voltage rejection ratio	vs Frequency	Figure 20
		vs Free-air temperature	Figure 21
I_{CC}	Supply current	vs Supply voltage	Figure 22
		vs Free-air temperature	Figure 23
V_n	Equivalent input noise voltage	vs Frequency	Figure 24
V_n	Input noise voltage	Over a 10-second period	Figure 25
I_n	Noise current	vs Frequency	Figure 26
THD+N	Total harmonic distortion plus noise	vs Frequency	Figure 27
SR	Slew rate	vs Free-air temperature	Figure 28
		vs Load capacitance	Figure 29
	Pulse response	Noninverting large signal	Figure 30
		Inverting large signal	Figure 31
		Small signal	Figure 32
B_1	Unity-gain bandwidth	vs Load capacitance	Figure 33
	Gain margin	vs Load capacitance	Figure 34
ϕ_m	Phase margin	vs Load capacitance	Figure 35

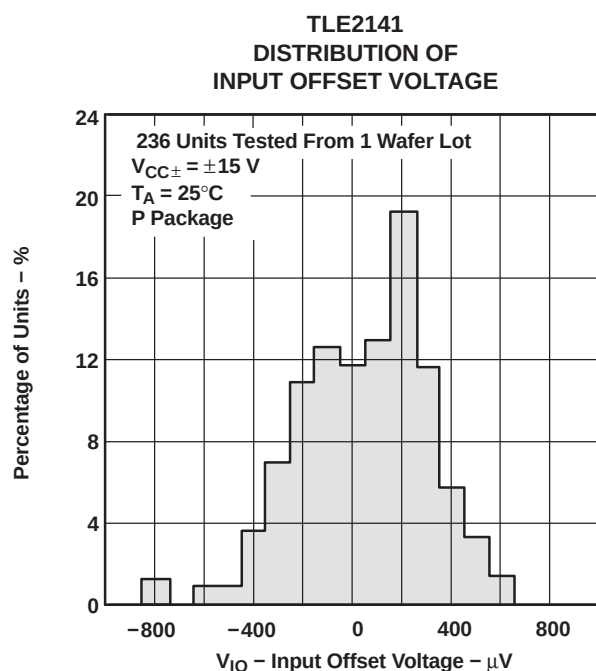


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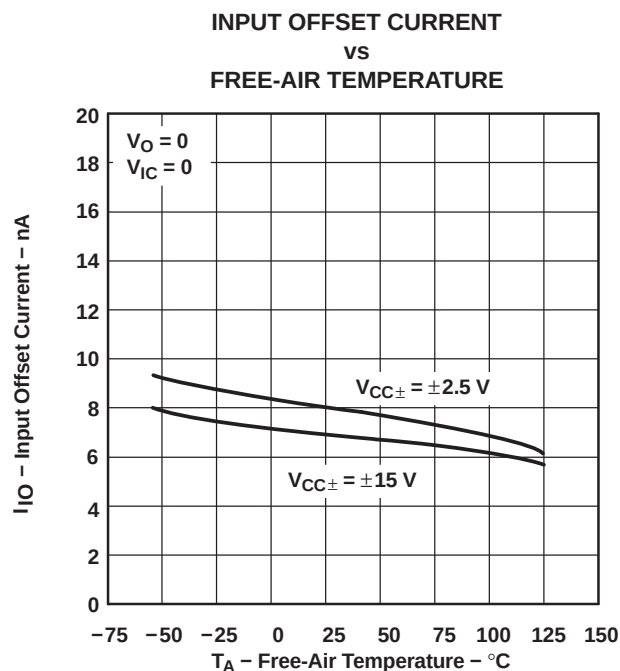


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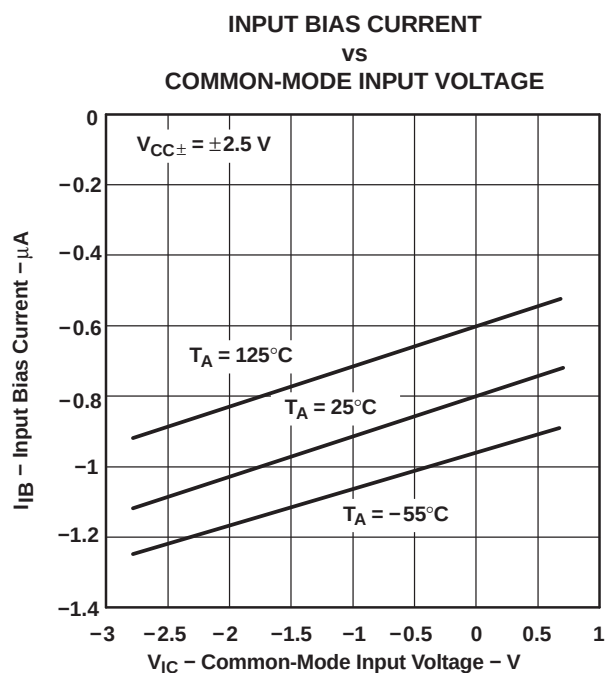


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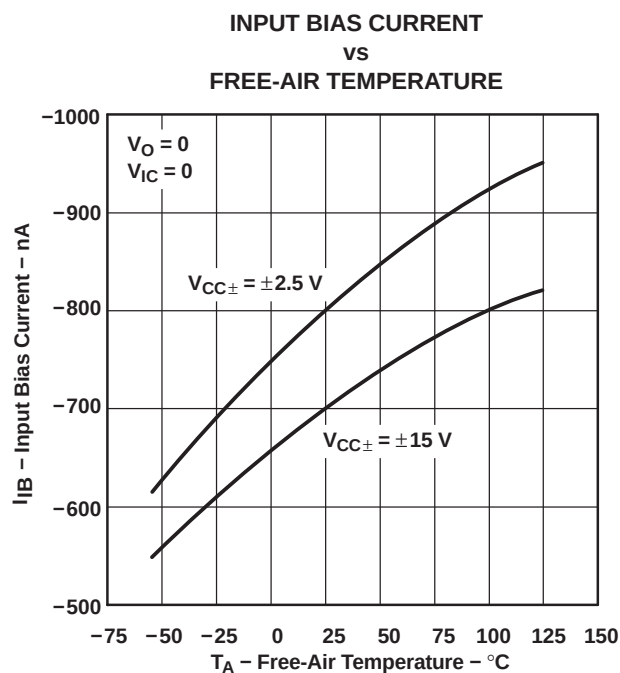


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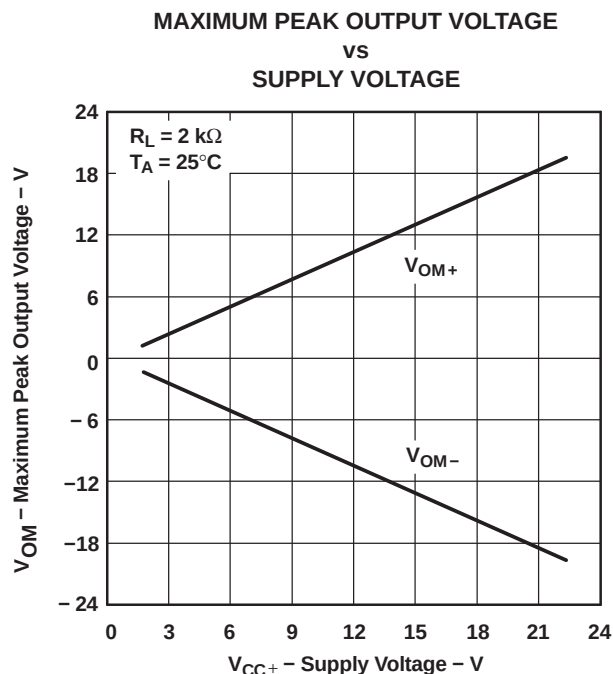


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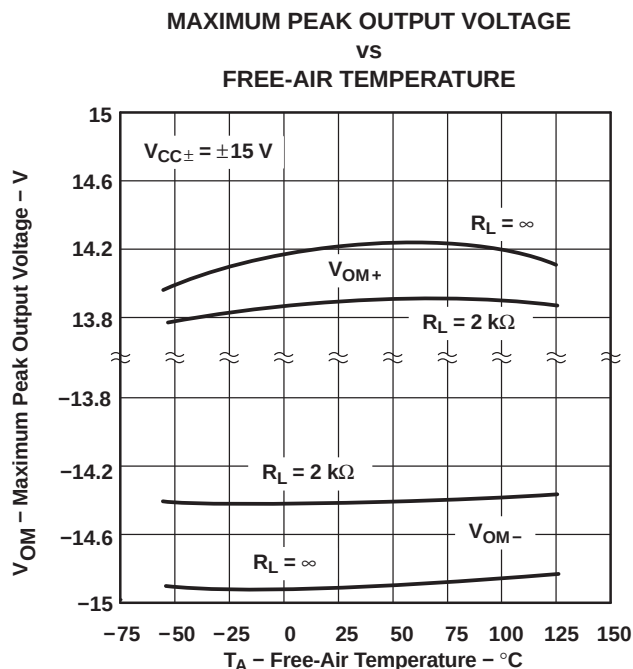


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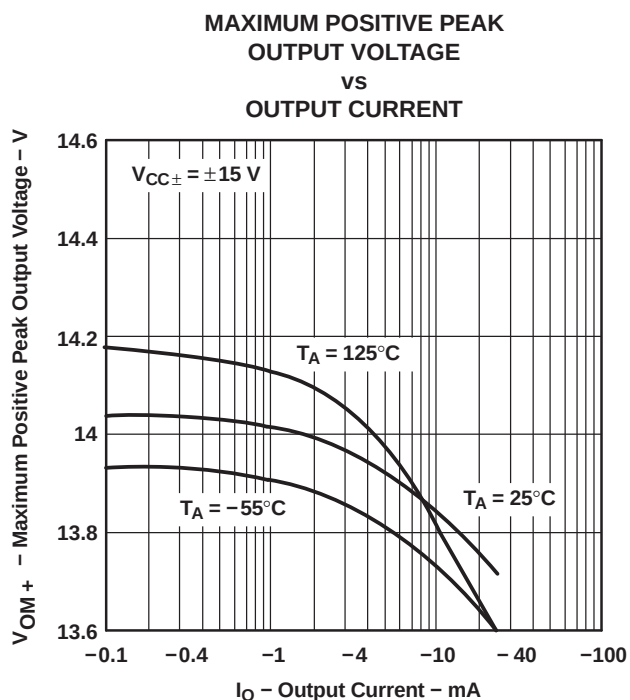


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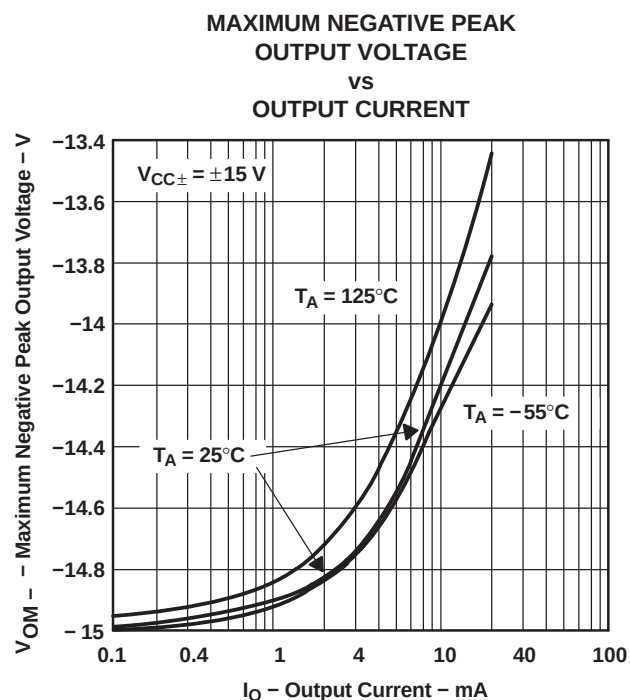


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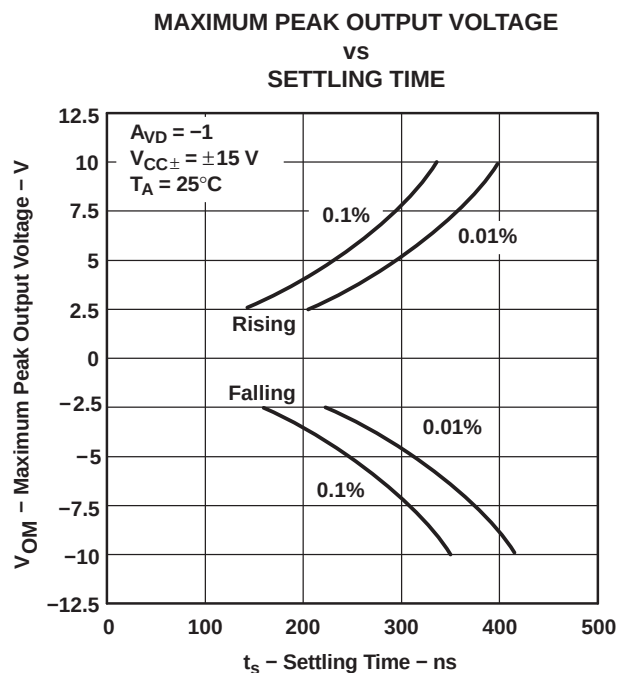


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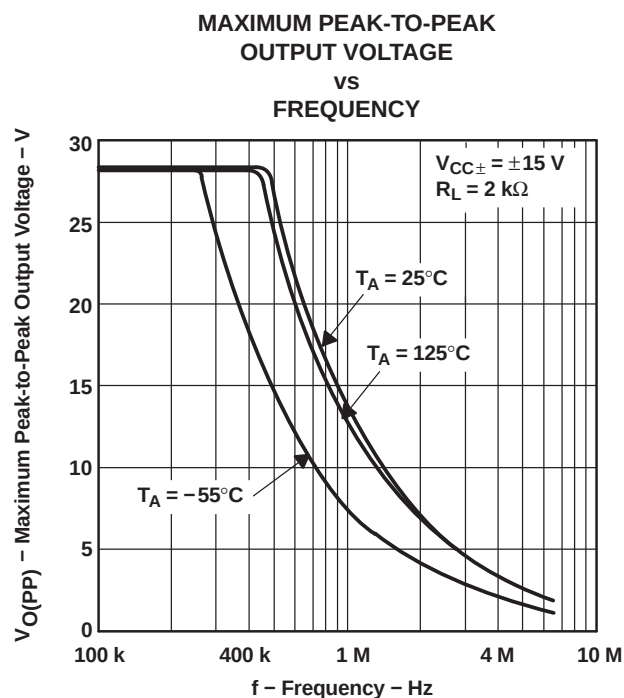


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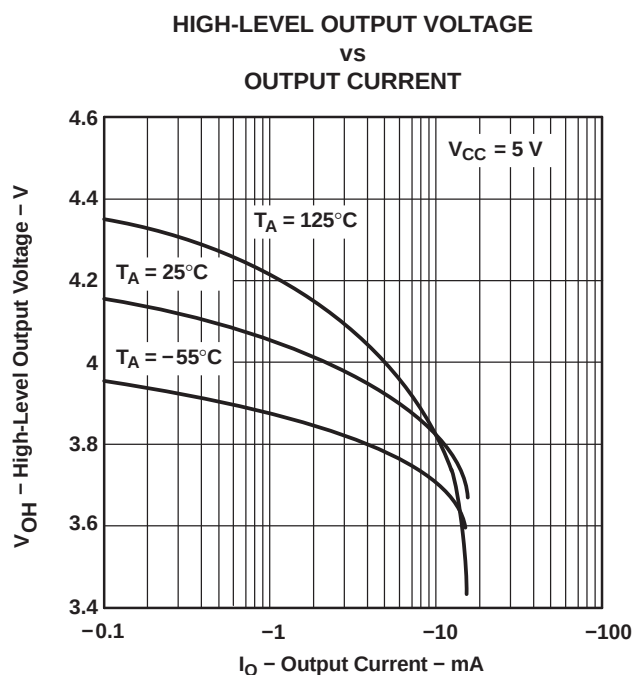


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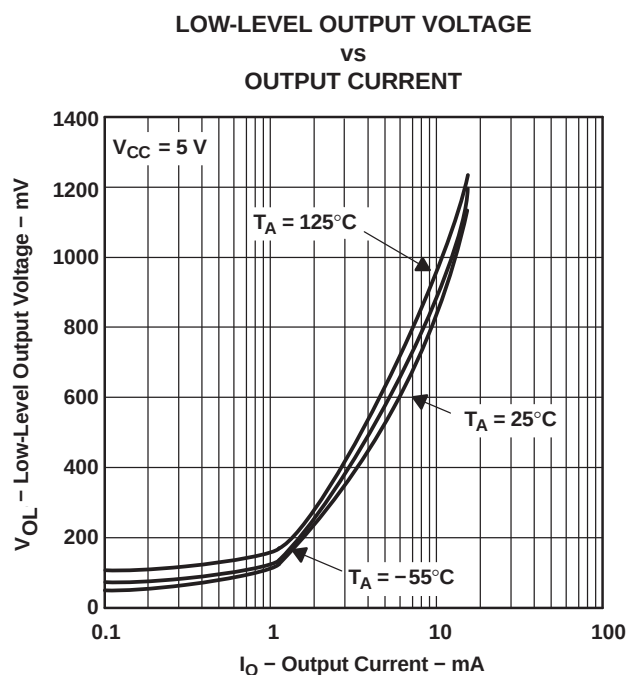


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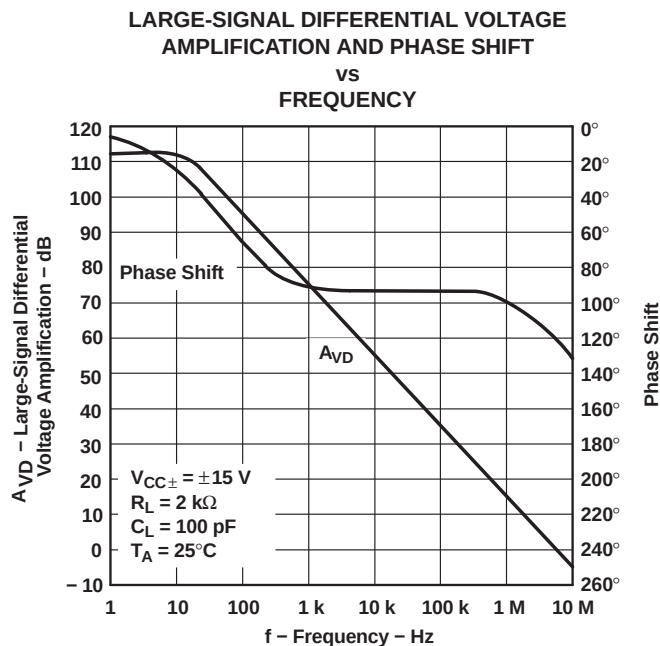


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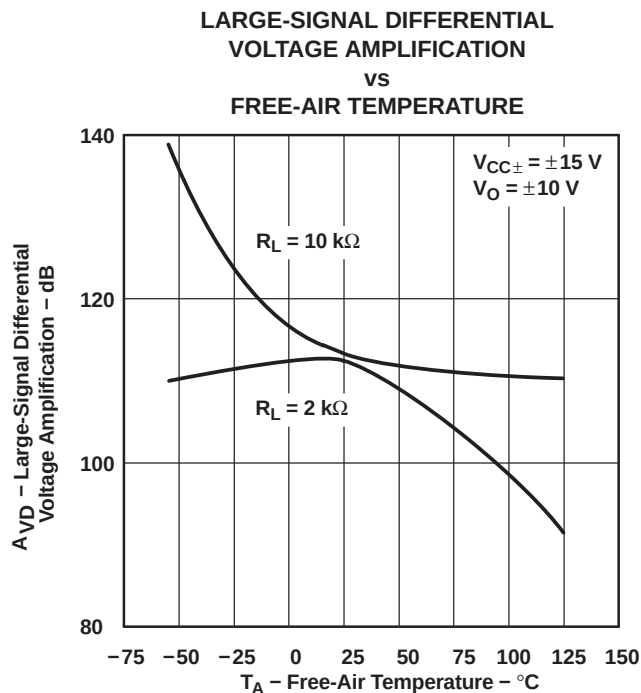


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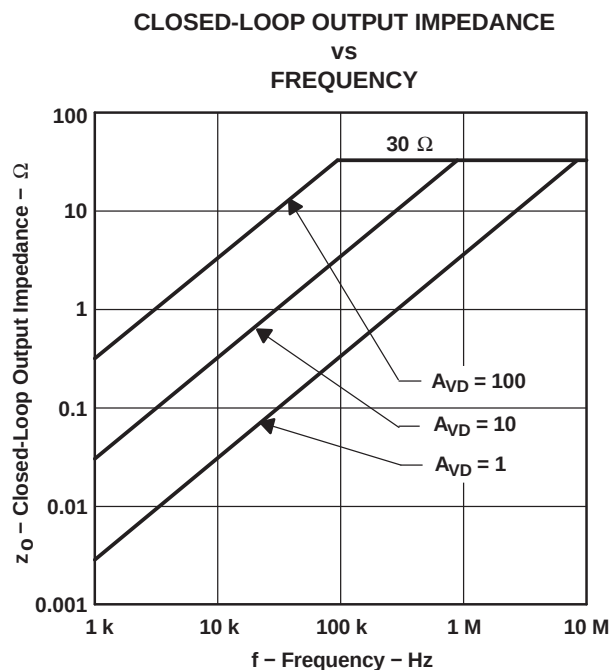


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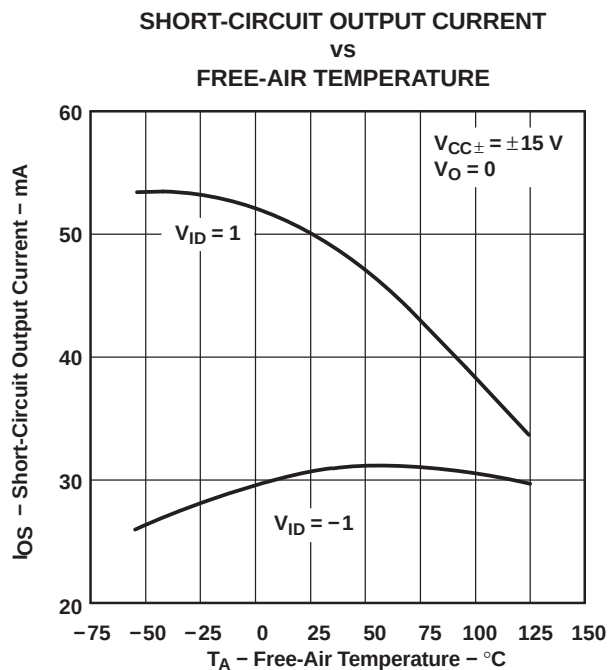


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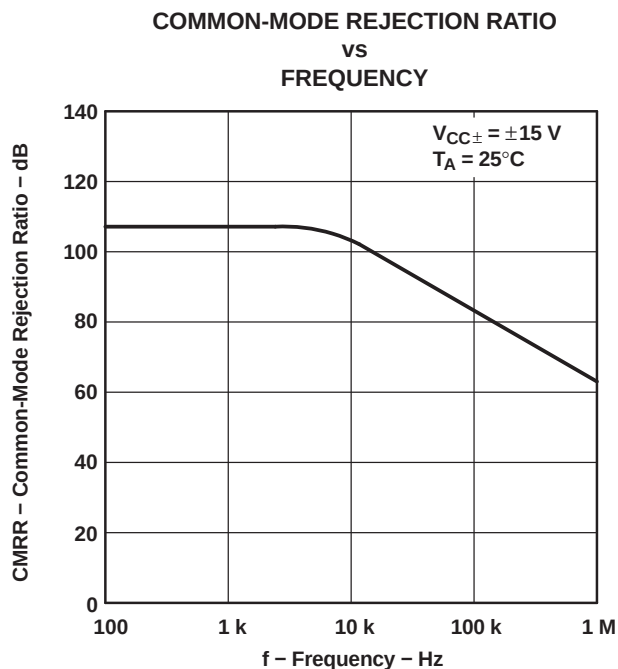


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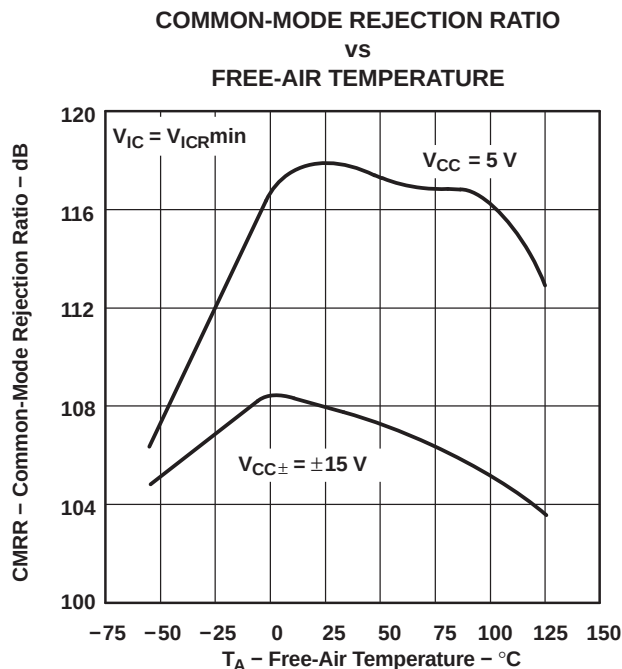


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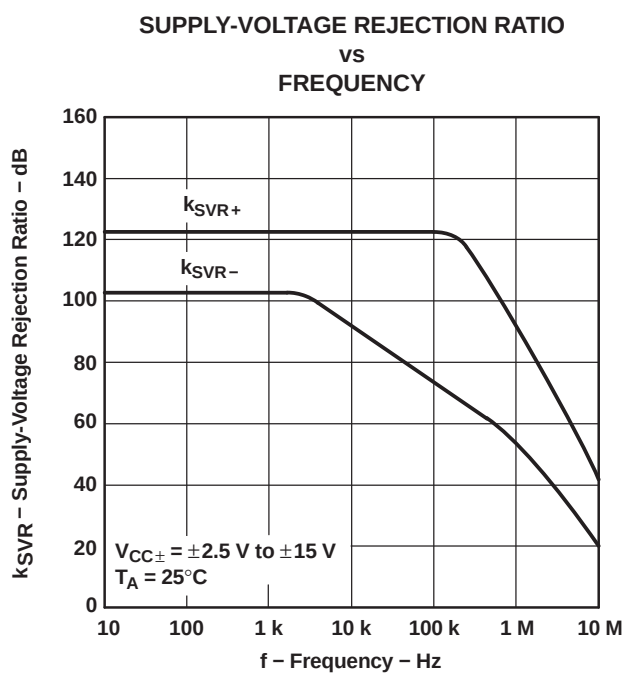


Figure 20.

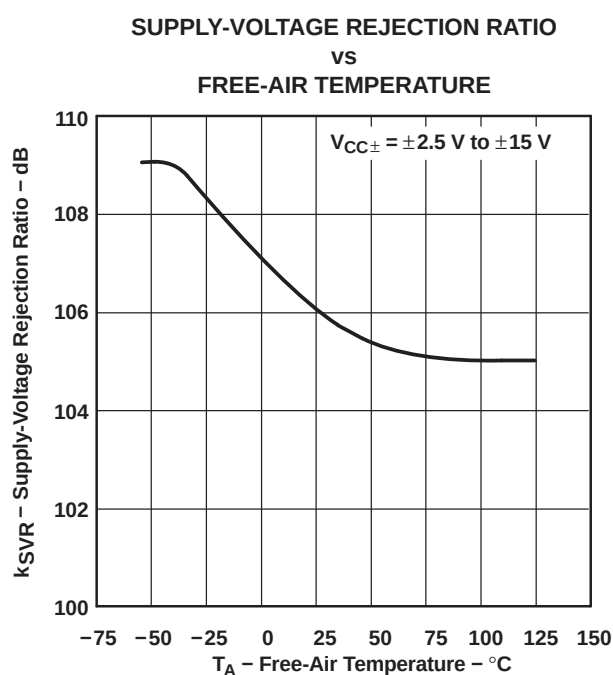


Figure 21.

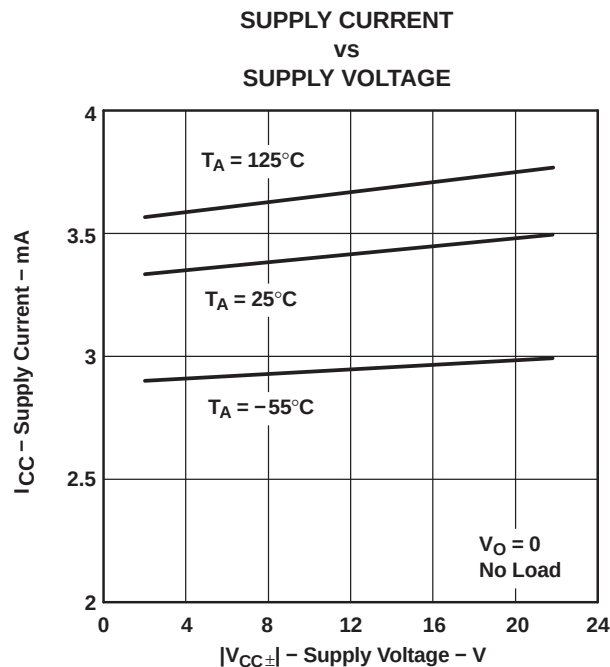


Figure 22.

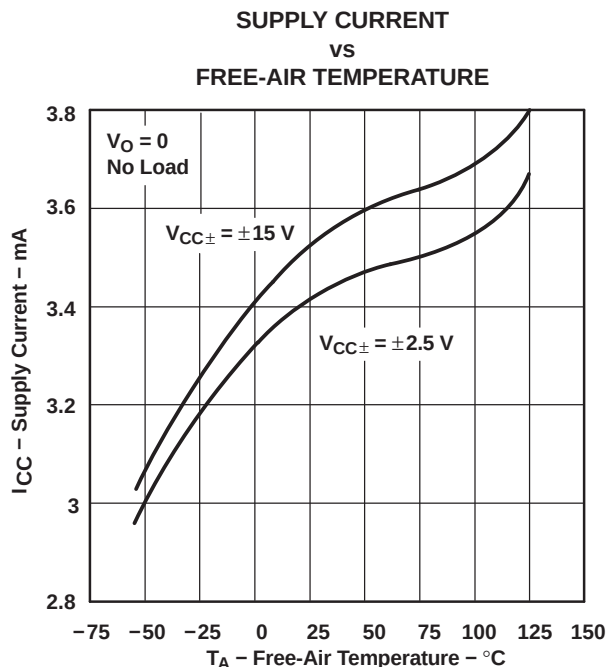


Figure 23.

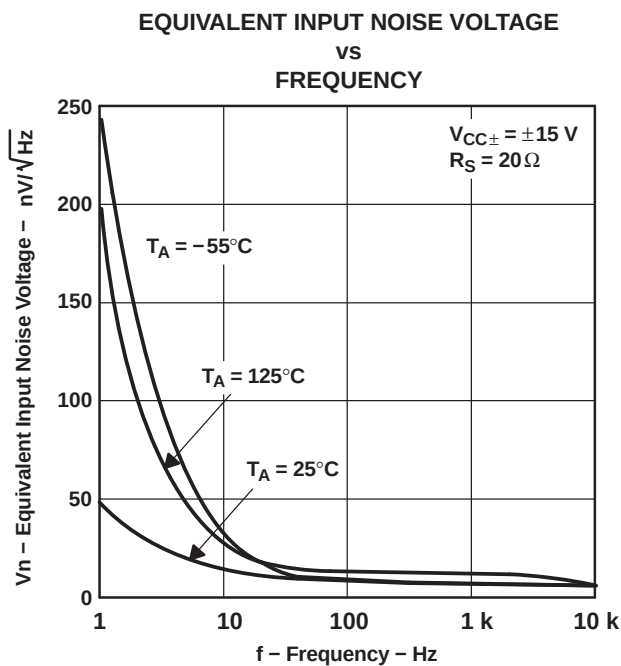


Figure 24.

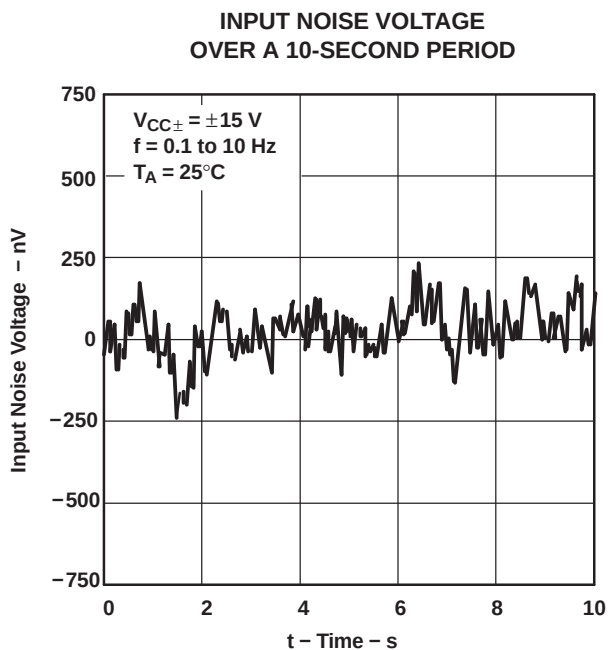


Figure 25.

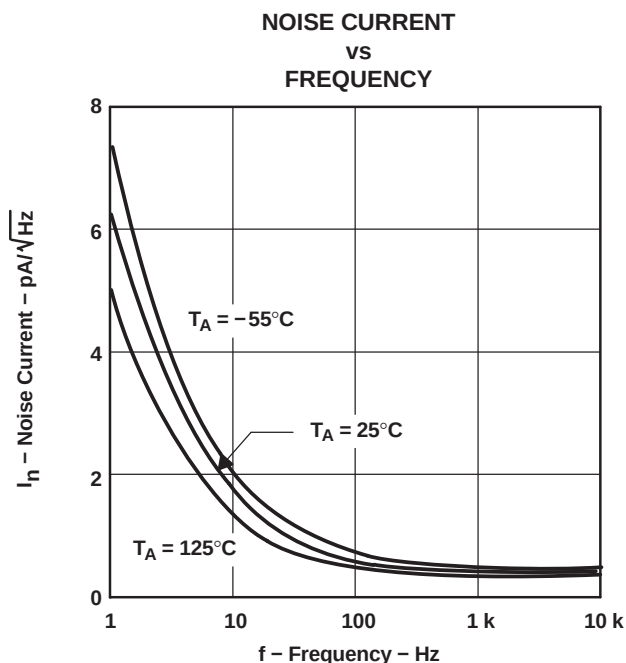


Figure 26.

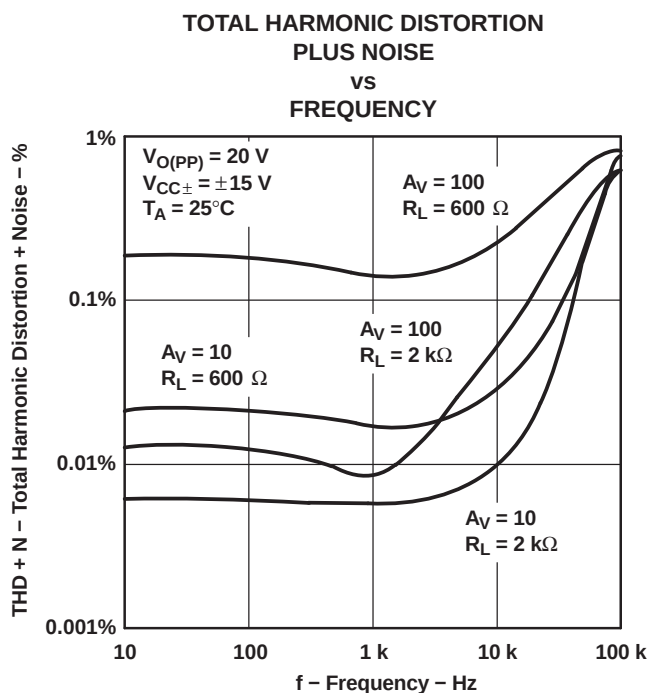


Figure 27.

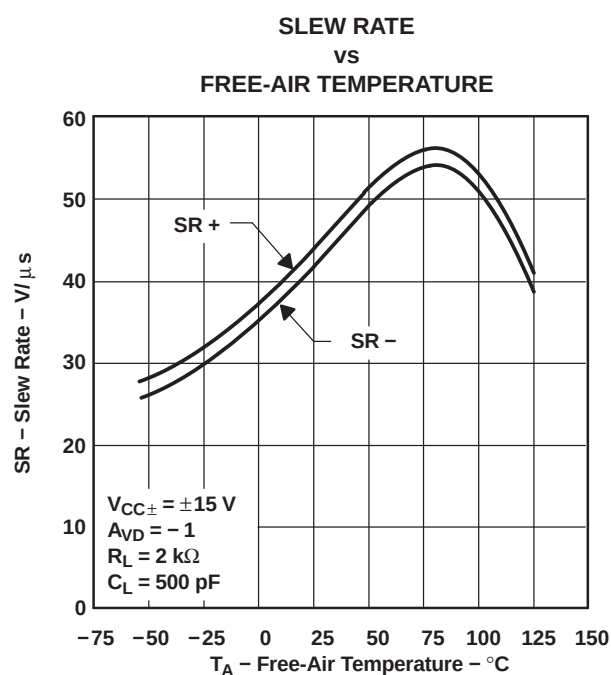


Figure 28.

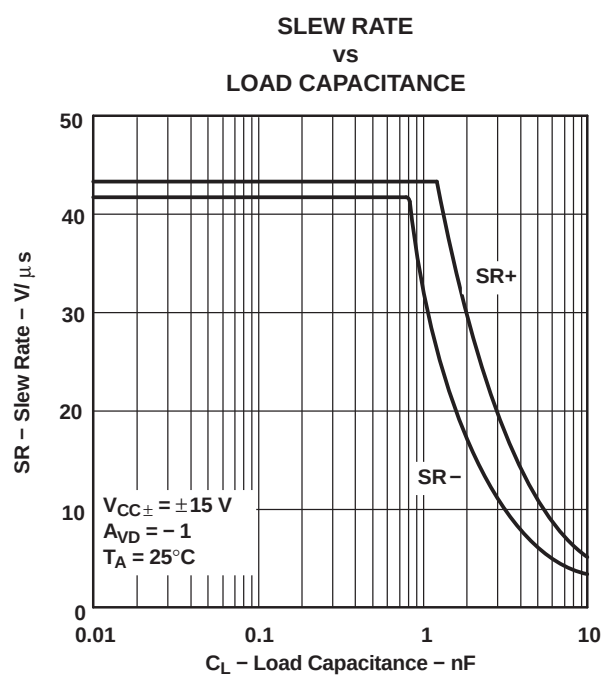
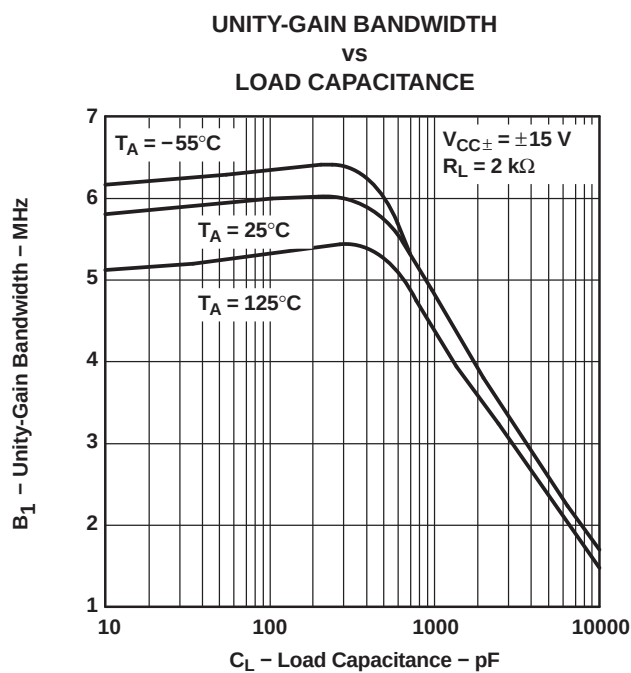
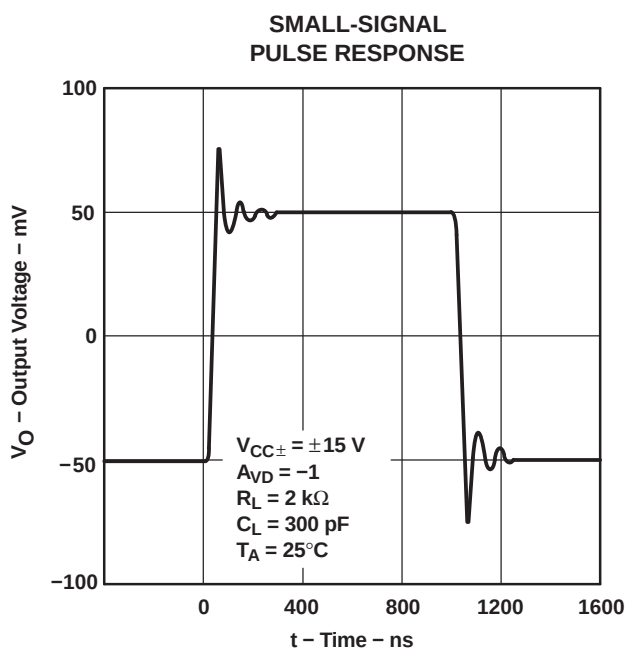
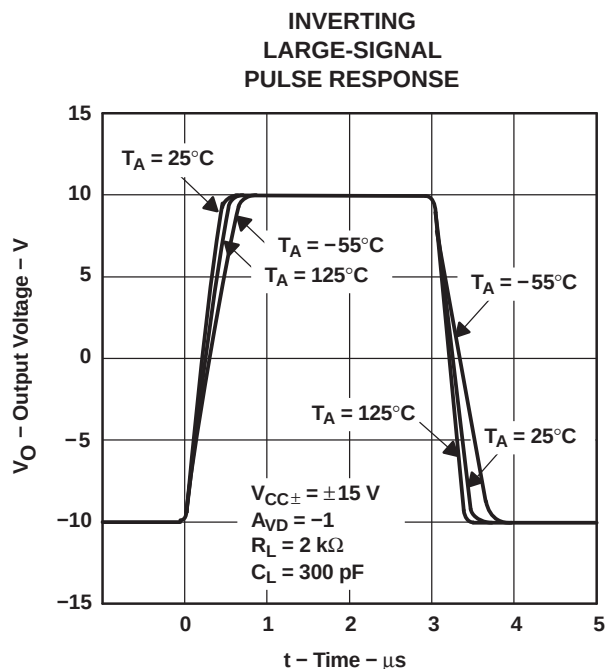
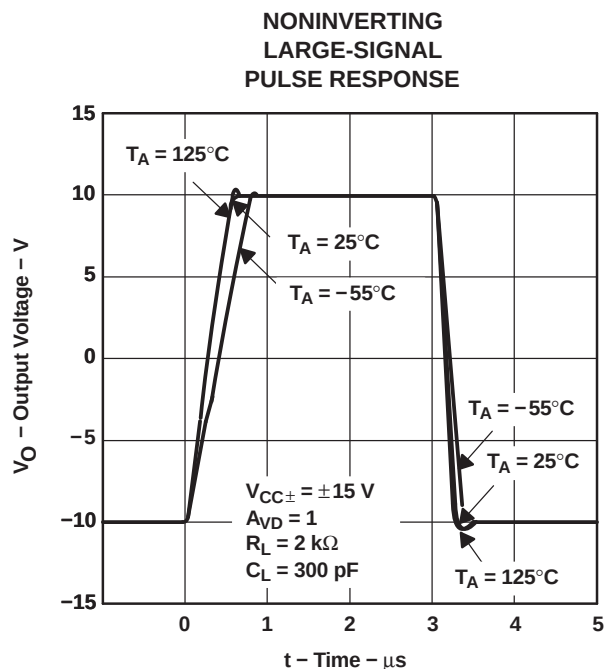


Figure 29.



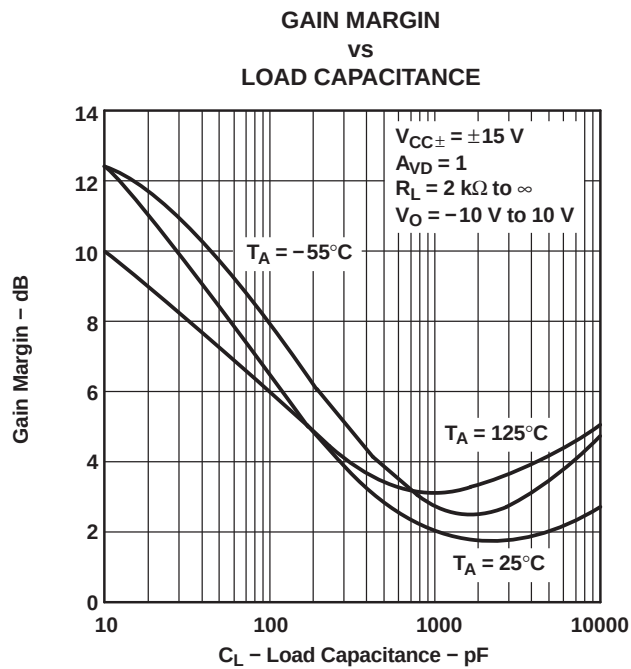


Figure 34.

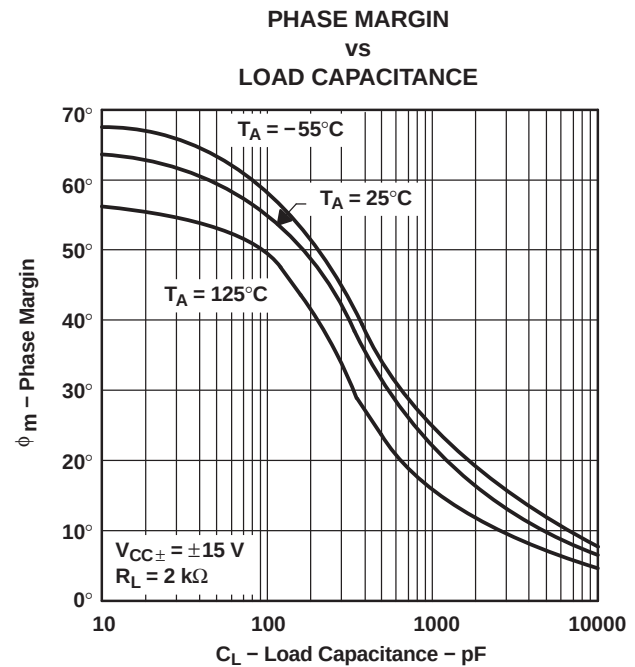


Figure 35.

APPLICATION INFORMATION

Input Offset Voltage Nulling

The TLE2141-Q1 offers external null pins that can be used to further reduce the input offset voltage. If this feature is desired, connect the circuit of [Figure 36](#) as shown. If external nulling is not needed, the null pins may be left unconnected.

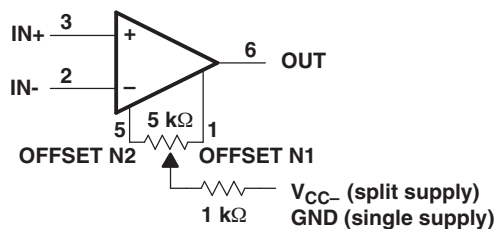


Figure 36. Input Offset Voltage Null Circuit

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
TLE2141QDRQ1	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	2141Q
TLE2141QDRQ1.A	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	2141Q

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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OTHER QUALIFIED VERSIONS OF TLE2141-Q1 :

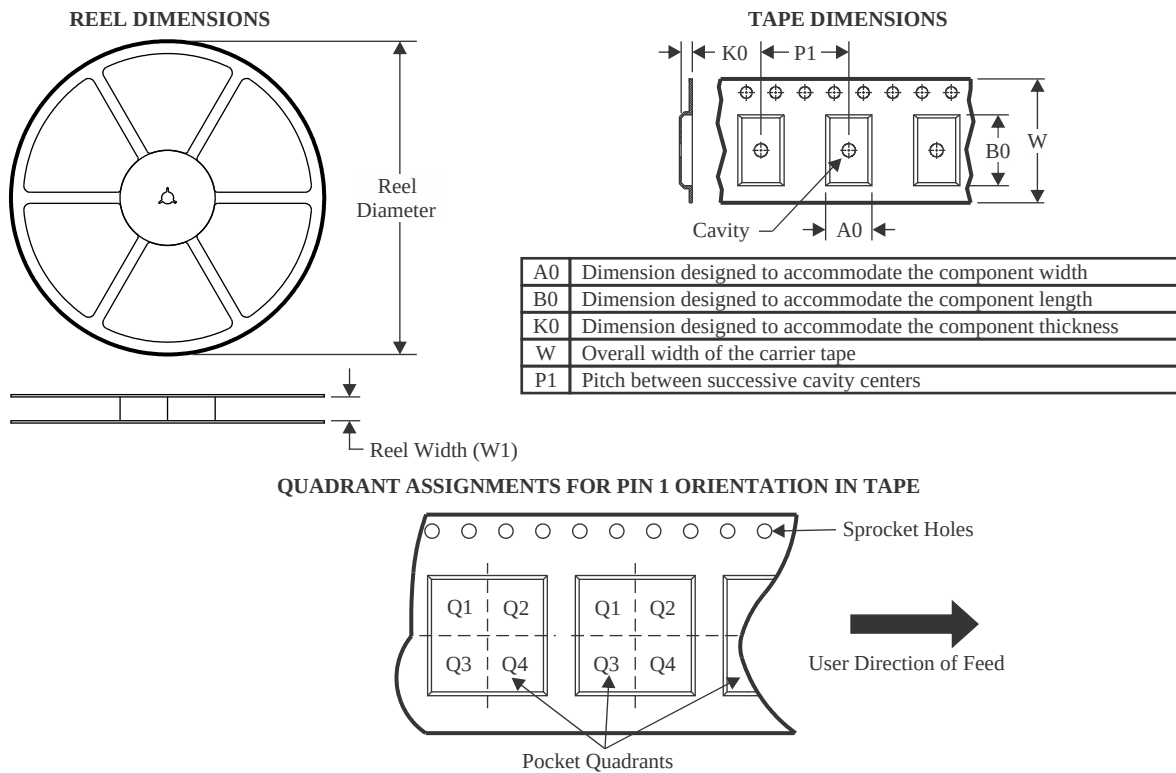
- Catalog : [TLE2141](#)

- Enhanced Product : [TLE2141-EP](#)
- Military : [TLE2141M](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Enhanced Product - Supports Defense, Aerospace and Medical Applications
- Military - QML certified for Military and Defense Applications

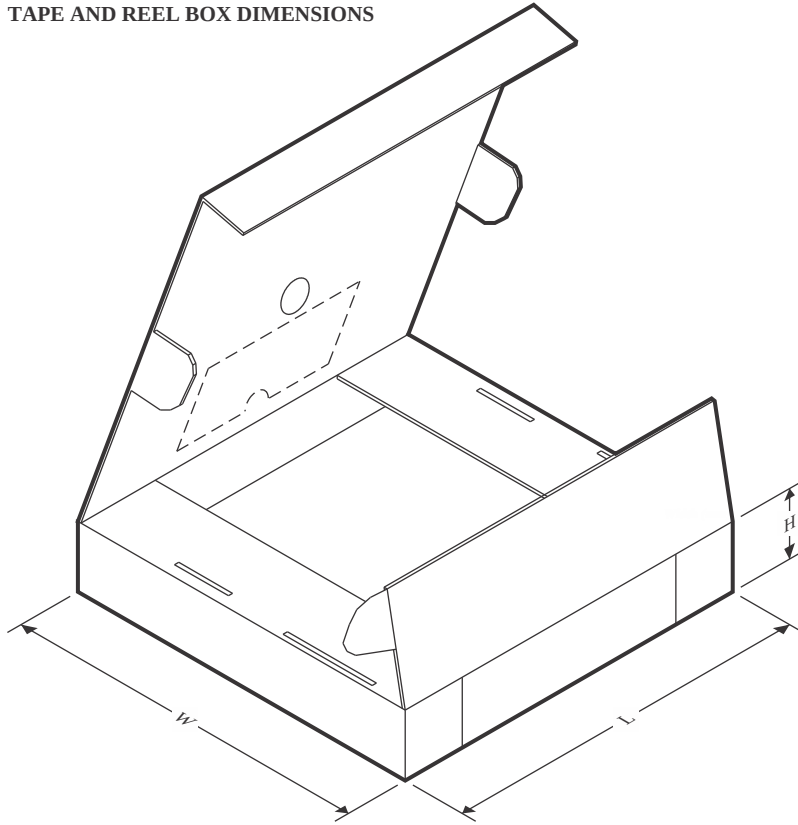
TAPE AND REEL INFORMATION



*All dimensions are nominal

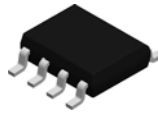
Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TLE2141QDRQ1	SOIC	D	8	2500	330.0	12.5	6.4	5.2	2.1	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TLE2141QDRQ1	SOIC	D	8	2500	353.0	353.0	32.0

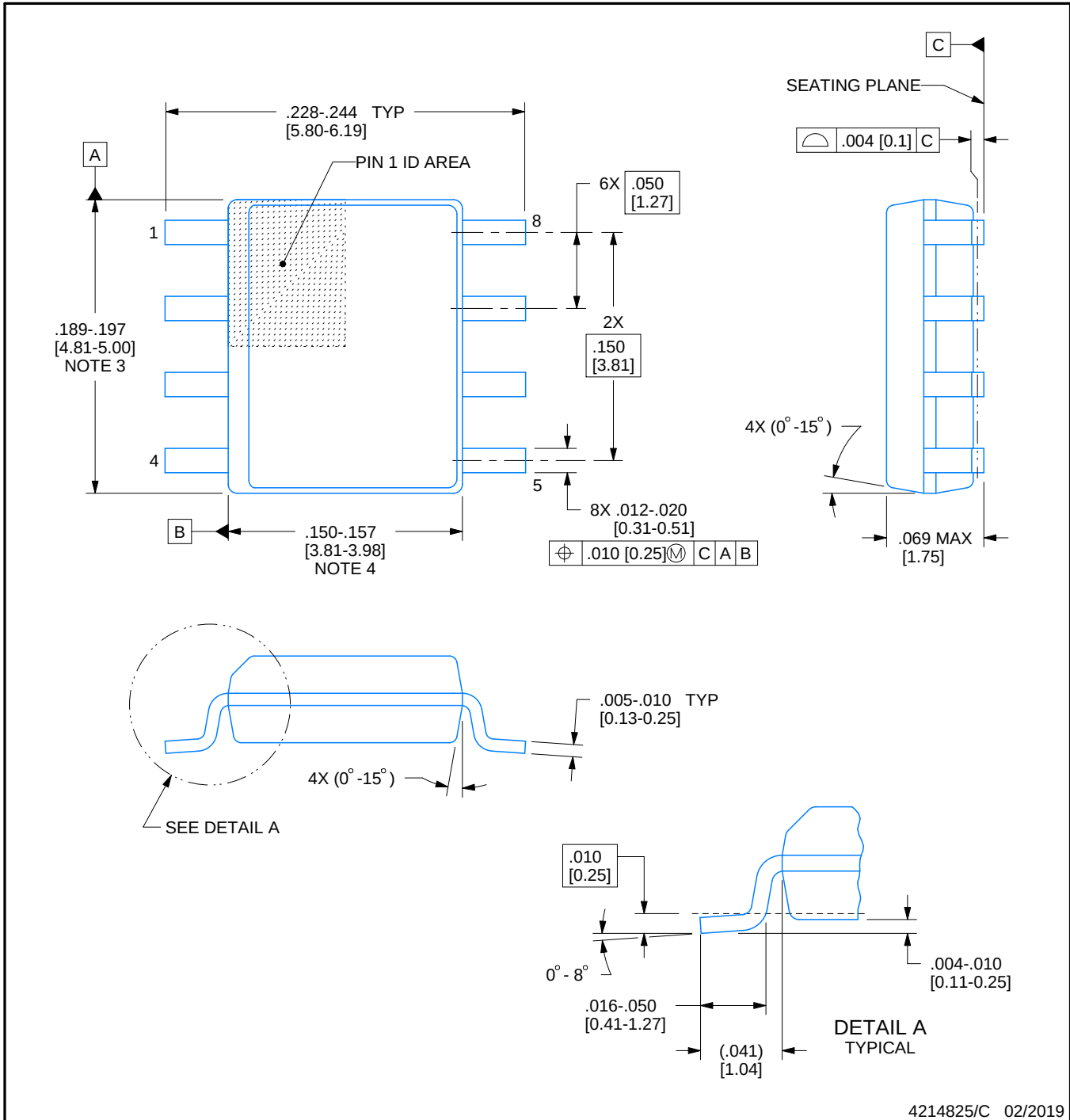


D0008A

PACKAGE OUTLINE

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



4214825/C 02/2019

NOTES:

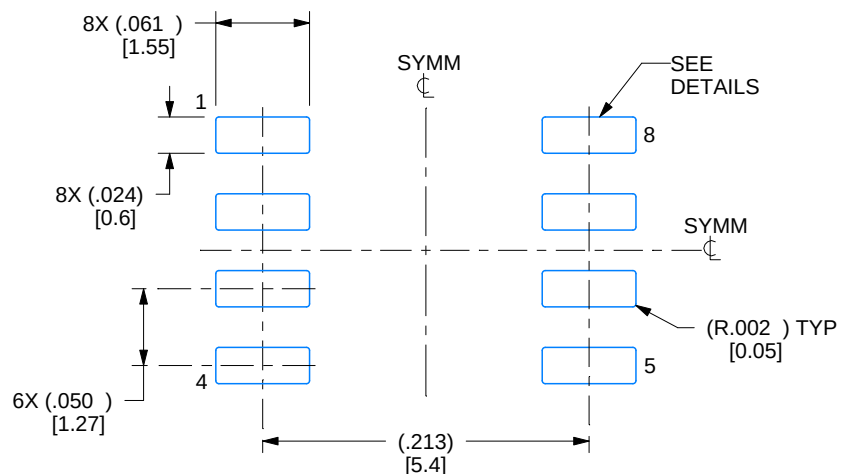
1. Linear dimensions are in inches [millimeters]. Dimensions in parenthesis are for reference only. Controlling dimensions are in inches. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 [0.15] per side.
4. This dimension does not include interlead flash.
5. Reference JEDEC registration MS-012, variation AA.

EXAMPLE BOARD LAYOUT

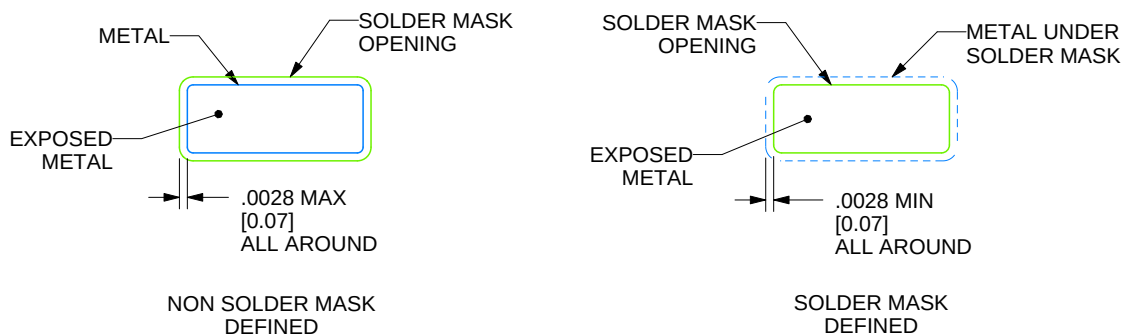
D0008A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:8X



SOLDER MASK DETAILS

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NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

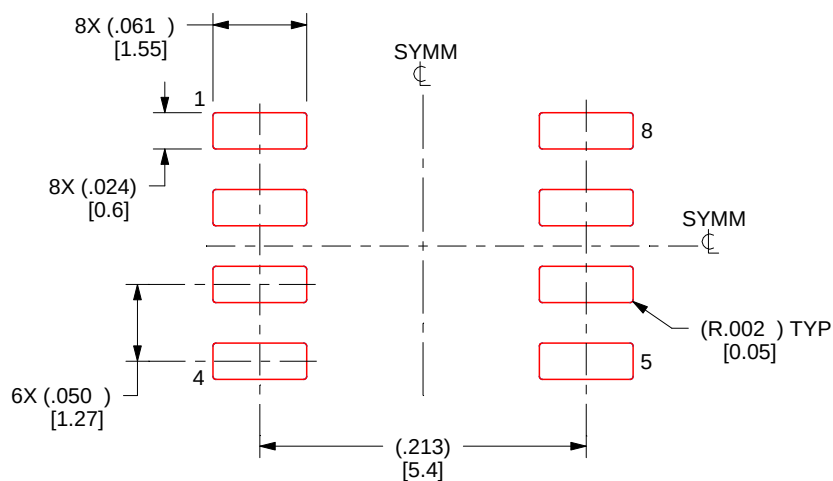
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

D0008A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



SOLDER PASTE EXAMPLE
BASED ON .005 INCH [0.125 MM] THICK STENCIL
SCALE:8X

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NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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